Renesas Electronics America Inc - R5F52316ADFM#30 Datasheet

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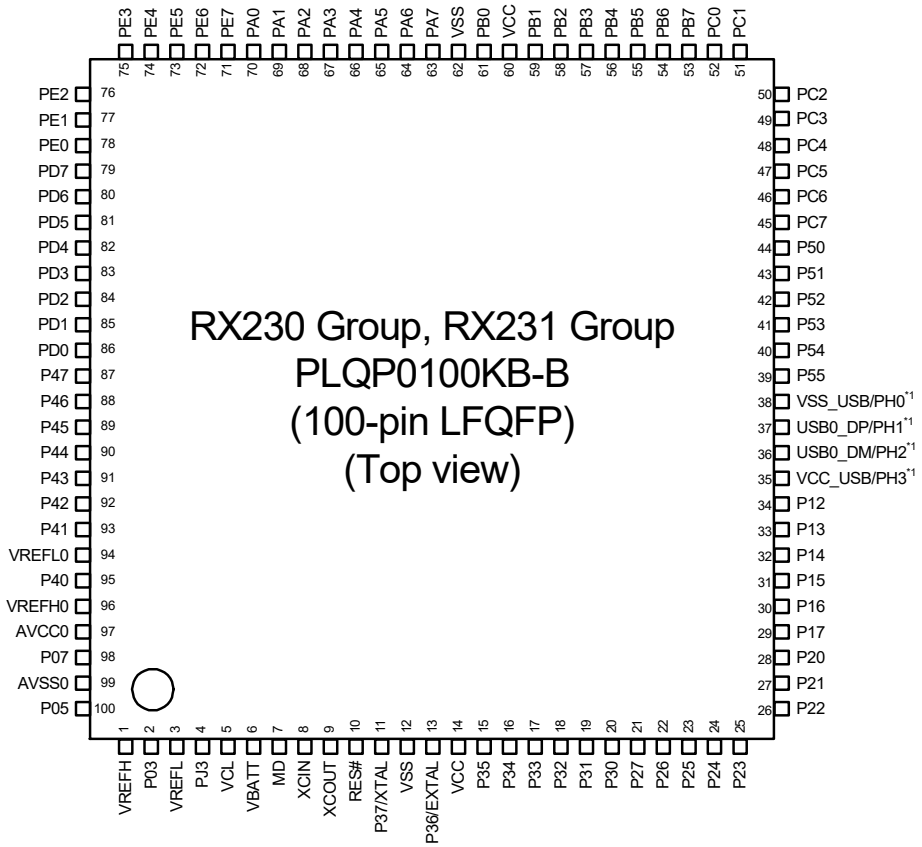
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	RXv2
Core Size	32-Bit Single-Core
Speed	54MHz
Connectivity	CANbus, I²C, IrDA, SCI, SD/SDIO, SPI, SSI, USB OTG
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	43
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f52316adfm-30



Note: This figure indicates the power supply pins and I/O port pins.
For the pin configuration, see the table “List of Pins and Pin Functions (100-Pin LFQFP)”.

Note 1. RX230: PH0, PH1, PH2, PH3
RX231: VSS_USB, USB0_DP, USB0_DM, VCC_USB

Figure 1.4 Pin Assignments of the 100-Pin LFQFP

Table 4.1 List of I/O Registers (Address Order) (11/33)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK <PCLK
0008 A0C9h	SCI6	I²C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB	2 ICLK
0008 A0CAh	SCI6	I²C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB	2 ICLK
0008 A0CBh	SCI6	I²C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB	2 ICLK
0008 A0CCh	SCI6	I²C Status Register	SISR	8	8	2 or 3 PCLKB	2 ICLK
0008 A0CDh	SCI6	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A0CEh	SCI6	Transmit Data Register HL	TDRHL	16	16	4 or 5 PCLKB	2 ICLK
0008 A0CEh	SCI6	Transmit Data Register H	TDRH	8	8	2 or 3 PCLKB	2 ICLK
0008 A0CFh	SCI6	Transmit Data Register L	TDRL	8	8	2 or 3 PCLKB	2 ICLK
0008 A0D0h	SCI6	Receive Data Register HL	RDRHL	16	16	4 or 5 PCLKB	2 ICLK
0008 A0D0h	SCI6	Receive Data Register H	RDRH	8	8	2 or 3 PCLKB	2 ICLK
0008 A0D1h	SCI6	Receive Data Register L	RDRL	8	8	2 or 3 PCLKB	2 ICLK
0008 A0D2h	SCI6	Modulation Duty Register	MDDR	8	8	2 or 3 PCLKB	2 ICLK
0008 A100h	SCI8	Serial Mode Register	SMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A101h	SCI8	Bit Rate Register	BRR	8	8	2 or 3 PCLKB	2 ICLK
0008 A102h	SCI8	Serial Control Register	SCR	8	8	2 or 3 PCLKB	2 ICLK
0008 A103h	SCI8	Transmit Data Register	TDR	8	8	2 or 3 PCLKB	2 ICLK
0008 A104h	SCI8	Serial Status Register	SSR	8	8	2 or 3 PCLKB	2 ICLK
0008 A105h	SCI8	Receive Data Register	RDR	8	8	2 or 3 PCLKB	2 ICLK
0008 A106h	SCI8	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A107h	SCI8	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A108h	SCI8	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB	2 ICLK
0008 A109h	SCI8	I²C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB	2 ICLK
0008 A10Ah	SCI8	I²C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB	2 ICLK
0008 A10Bh	SCI8	I²C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB	2 ICLK
0008 A10Ch	SCI8	I²C Status Register	SISR	8	8	2 or 3 PCLKB	2 ICLK
0008 A10Dh	SCI8	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A10Eh	SCI8	Transmit Data Register HL	TDRHL	16	16	4 or 5 PCLKB	2 ICLK
0008 A10Eh	SCI8	Transmit Data Register H	TDRH	8	8	2 or 3 PCLKB	2 ICLK
0008 A10Fh	SCI8	Transmit Data Register L	TDRL	8	8	2 or 3 PCLKB	2 ICLK
0008 A110h	SCI8	Receive Data Register HL	RDRHL	16	16	4 or 5 PCLKB	2 ICLK
0008 A110h	SCI8	Receive Data Register H	RDRH	8	8	2 or 3 PCLKB	2 ICLK
0008 A111h	SCI8	Receive Data Register L	RDRL	8	8	2 or 3 PCLKB	2 ICLK
0008 A112h	SCI8	Modulation Duty Register	MDDR	8	8	2 or 3 PCLKB	2 ICLK
0008 A120h	SCI9	Serial Mode Register	SMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A121h	SCI9	Bit Rate Register	BRR	8	8	2 or 3 PCLKB	2 ICLK
0008 A122h	SCI9	Serial Control Register	SCR	8	8	2 or 3 PCLKB	2 ICLK
0008 A123h	SCI9	Transmit Data Register	TDR	8	8	2 or 3 PCLKB	2 ICLK
0008 A124h	SCI9	Serial Status Register	SSR	8	8	2 or 3 PCLKB	2 ICLK
0008 A125h	SCI9	Receive Data Register	RDR	8	8	2 or 3 PCLKB	2 ICLK
0008 A126h	SCI9	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A127h	SCI9	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A128h	SCI9	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB	2 ICLK
0008 A129h	SCI9	I²C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB	2 ICLK
0008 A12Ah	SCI9	I²C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB	2 ICLK
0008 A12Bh	SCI9	I²C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB	2 ICLK
0008 A12Ch	SCI9	I²C Status Register	SISR	8	8	2 or 3 PCLKB	2 ICLK
0008 A12Dh	SCI9	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A12Eh	SCI9	Transmit Data Register HL	TDRHL	16	16	4 or 5 PCLKB	2 ICLK
0008 A12Eh	SCI9	Transmit Data Register H	TDRH	8	8	2 or 3 PCLKB	2 ICLK
0008 A12Fh	SCI9	Transmit Data Register L	TDRL	8	8	2 or 3 PCLKB	2 ICLK
0008 A130h	SCI9	Receive Data Register HL	RDRHL	16	16	4 or 5 PCLKB	2 ICLK
0008 A130h	SCI9	Receive Data Register H	RDRH	8	8	2 or 3 PCLKB	2 ICLK

Table 4.1 List of I/O Registers (Address Order) (12/33)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK <PCLK
0008 A131h	SCI9	Receive Data Register L	RDRL	8	8	2 or 3 PCLKB	2 ICLK
0008 A132h	SCI9	Modulation Duty Register	MDDR	8	8	2 or 3 PCLKB	2 ICLK
0008 A500h	SSI0	Control Register	SSICR	32	32	2 or 3 PCLKB	2 ICLK
0008 A504h	SSI0	Status Register	SSISR	32	32	2 or 3 PCLKB	2 ICLK
0008 A510h	SSI0	FIFO Control Register	SSIFCR	32	32	2 or 3 PCLKB	2 ICLK
0008 A514h	SSI0	FIFO Status Register	SSIFSR	32	32	2 or 3 PCLKB	2 ICLK
0008 A518h	SSI0	Transmit FIFO Data Register	SSIFTDR	32	32	2 or 3 PCLKB	2 ICLK
0008 A51Ch	SSI0	Receive FIFO Data Register	SSIFRDR	32	32	2 or 3 PCLKB	2 ICLK
0008 A520h	SSI0	TDM Mode Register	SSITDMR	32	32	2 or 3 PCLKB	2 ICLK
0008 AC00h	SDHI	Command Register	SDCMD	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC08h	SDHI	Argument Register	SDARG	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC10h	SDHI	Data Stop Register	SDSTOP	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC14h	SDHI	Block Count Register	SDBLKCNT	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC18h	SDHI	Response Register 10	SDRSP10	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC20h	SDHI	Response Register 32	SDRSP32	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC28h	SDHI	Response Register 54	SDRSP54	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC30h	SDHI	Response Register 76	SDRSP76	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC38h	SDHI	SD Status Register 1	SDSTS1	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC3Ch	SDHI	SD Status Register 2	SDSTS2	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing
0008 AC40h	SDHI	SD Interrupt Mask Register 1	SDIMSK1	32	32	3 or 4 PCLKB cycles when reading, 2 or 3 PCLKB cycles when writing	3 ICLK cycles when reading, 2 ICLK cycles when writing

Table 4.1 List of I/O Registers (Address Order) (20/33)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK <PCLK
0008 C42Eh	RTC	Time Error Adjustment Register	RADJ	8	8	2 or 3 PCLKB	2 ICLK
0008 C440h	RTC	Time Capture Control Register 0	RTCCR0	8	8	2 or 3 PCLKB	2 ICLK
0008 C442h	RTC	Time Capture Control Register 1	RTCCR1	8	8	2 or 3 PCLKB	2 ICLK
0008 C444h	RTC	Time Capture Control Register 2	RTCCR2	8	8	2 or 3 PCLKB	2 ICLK
0008 C452h	RTC	Second Capture Register 0	RSECCP0	8	8	2 or 3 PCLKB	2 ICLK
0008 C452h	RTC	BCNT0 Capture Register 0	BCNT0CP0	8	8	2 or 3 PCLKB	2 ICLK
0008 C454h	RTC	Minute Capture Register 0	RMINCP0	8	8	2 or 3 PCLKB	2 ICLK
0008 C454h	RTC	BCNT1 Capture Register 0	BCNT1CP0	8	8	2 or 3 PCLKB	2 ICLK
0008 C456h	RTC	Hour Capture Register 0	RHRCP0	8	8	2 or 3 PCLKB	2 ICLK
0008 C456h	RTC	BCNT2 Capture Register 0	BCNT2CP0	8	8	2 or 3 PCLKB	2 ICLK
0008 C45Ah	RTC	Date Capture Register 0	RDAYCP0	8	8	2 or 3 PCLKB	2 ICLK
0008 C45Ah	RTC	BCNT3 Capture Register 0	BCNT3CP0	8	8	2 or 3 PCLKB	2 ICLK
0008 C45Ch	RTC	Month Capture Register 0	RMONCP0	8	8	2 or 3 PCLKB	2 ICLK
0008 C462h	RTC	Second Capture Register 1	RSECCP1	8	8	2 or 3 PCLKB	2 ICLK
0008 C462h	RTC	BCNT0 Capture Register 1	BCNT0CP1	8	8	2 or 3 PCLKB	2 ICLK
0008 C464h	RTC	Minute Capture Register 1	RMINCP1	8	8	2 or 3 PCLKB	2 ICLK
0008 C464h	RTC	BCNT1 Capture Register 1	BCNT1CP1	8	8	2 or 3 PCLKB	2 ICLK
0008 C466h	RTC	Hour Capture Register 1	RHRCP1	8	8	2 or 3 PCLKB	2 ICLK
0008 C466h	RTC	BCNT2 Capture Register 1	BCNT2CP1	8	8	2 or 3 PCLKB	2 ICLK
0008 C46Ah	RTC	Date Capture Register 1	RDAYCP1	8	8	2 or 3 PCLKB	2 ICLK
0008 C46Ah	RTC	BCNT3 Capture Register 1	BCNT3CP1	8	8	2 or 3 PCLKB	2 ICLK
0008 C46Ch	RTC	Month Capture Register 1	RMONCP1	8	8	2 or 3 PCLKB	2 ICLK
0008 C472h	RTC	Second Capture Register 2	RSECCP2	8	8	2 or 3 PCLKB	2 ICLK
0008 C472h	RTC	BCNT0 Capture Register 2	BCNT0CP2	8	8	2 or 3 PCLKB	2 ICLK
0008 C474h	RTC	Minute Capture Register 2	RMINCP2	8	8	2 or 3 PCLKB	2 ICLK
0008 C474h	RTC	BCNT1 Capture Register 2	BCNT1CP2	8	8	2 or 3 PCLKB	2 ICLK
0008 C476h	RTC	Hour Capture Register 2	RHRCP2	8	8	2 or 3 PCLKB	2 ICLK
0008 C476h	RTC	BCNT2 Capture Register 2	BCNT2CP2	8	8	2 or 3 PCLKB	2 ICLK
0008 C47Ah	RTC	Date Capture Register 2	RDAYCP2	8	8	2 or 3 PCLKB	2 ICLK
0008 C47Ah	RTC	BCNT3 Capture Register 2	BCNT3CP2	8	8	2 or 3 PCLKB	2 ICLK
0008 C47Ch	RTC	Month Capture Register 2	RMONCP2	8	8	2 or 3 PCLKB	2 ICLK
0008 C580h	CMPB	Comparator B Control Register 1	CPBCNT1	8	8	2 or 3 PCLKB	2 ICLK
0008 C581h	CMPB	Comparator B Control Register 2	CPBCNT2	8	8	2 or 3 PCLKB	2 ICLK
0008 C582h	CMPB	Comparator B Flag Register	CPBFLG	8	8	2 or 3 PCLKB	2 ICLK
0008 C583h	CMPB	Comparator B Interrupt Control Register	CPBINT	8	8	2 or 3 PCLKB	2 ICLK
0008 C584h	CMPB	Comparator B Filter Select Register	CPBF	8	8	2 or 3 PCLKB	2 ICLK
0008 C585h	CMPB	Comparator B Mode Select Register	CPBMD	8	8	2 or 3 PCLKB	2 ICLK
0008 C586h	CMPB	Comparator B Reference Input Voltage Select Register	CPBREF	8	8	2 or 3 PCLKB	2 ICLK
0008 C587h	CMPB	Comparator B Output Control Register	CPBOCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C5A0h	CMPB	Comparator B1 Control Register 1	CPB1CNT1	8	8	2 or 3 PCLKB	2 ICLK
0008 C5A1h	CMPB	Comparator B1 Control Register 2	CPB1CNT2	8	8	2 or 3 PCLKB	2 ICLK
0008 C5A2h	CMPB	Comparator B1 Flag Register	CPB1FLG	8	8	2 or 3 PCLKB	2 ICLK
0008 C5A3h	CMPB	Comparator B1 Interrupt Control Register	CPB1INT	8	8	2 or 3 PCLKB	2 ICLK
0008 C5A4h	CMPB	Comparator B1 Filter Select Register	CPB1F	8	8	2 or 3 PCLKB	2 ICLK
0008 C5A5h	CMPB	Comparator B1 Mode Select Register	CPB1MD	8	8	2 or 3 PCLKB	2 ICLK
0008 C5A6h	CMPB	Comparator B1 Reference Input Voltage Select Register	CPB1REF	8	8	2 or 3 PCLKB	2 ICLK
0008 C5A7h	CMPB	Comparator B1 Output Control Register	CPB1OCR	8	8	2 or 3 PCLKB	2 ICLK
000A 0000h	USB0	System Configuration Control Register	SYSCFG	16	16	3, 4 PCLKB	2 ICLK
000A 0004h	USB0	System Configuration Status Register 0	SYSSTS0	16	16	9 PCLKB or more	Rounded up to the nearest integer greater than 1 + 9 × (frequency ratio of ICLK/PCLKB)*2

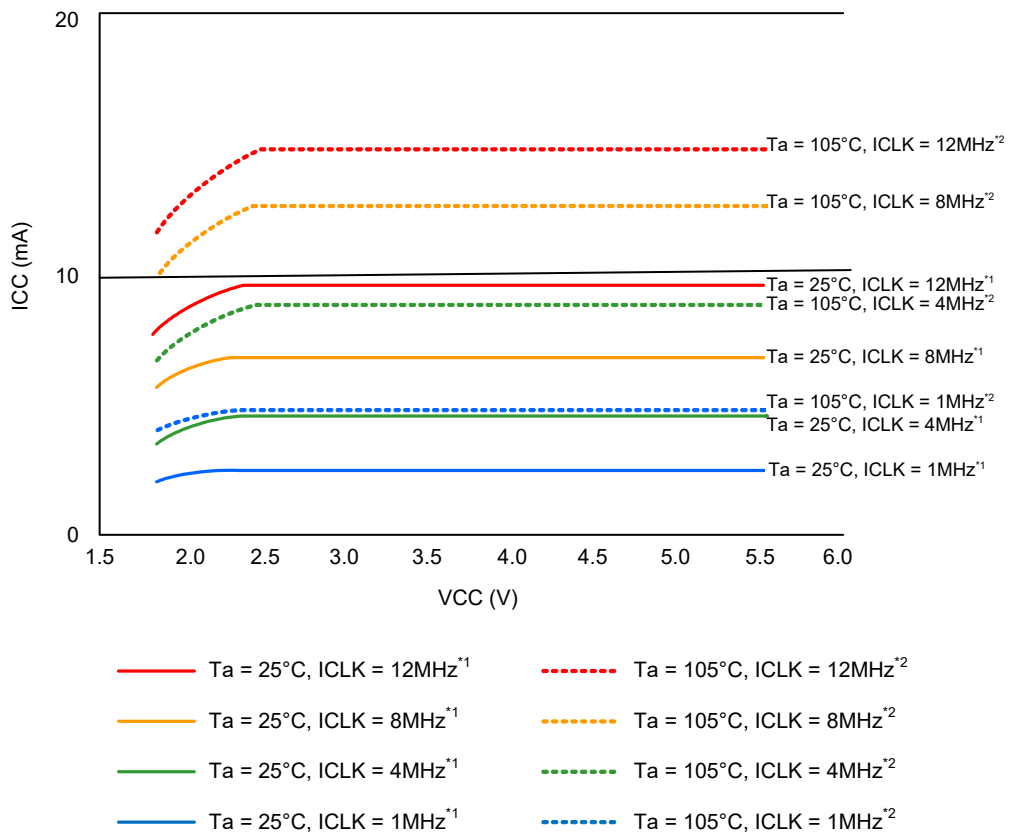
Table 4.1 List of I/O Registers (Address Order) (30/33)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK <PCLK
000A 85EAh	RSCAN0	Transmit/Receive FIFO Access Register 0CH	CFDF10	16	16	2 or 3 PCLKB	2 ICLK
000A 85EAh	RSCAN	RAM Test Register 53	RPGACC53	16	16	2 or 3 PCLKB	2 ICLK
000A 85ECh	RSCAN0	Transmit/Receive FIFO Access Register 0DL	CFDF20	16	16	2 or 3 PCLKB	2 ICLK
000A 85ECh	RSCAN	RAM Test Register 54	RPGACC54	16	16	2 or 3 PCLKB	2 ICLK
000A 85EEh	RSCAN0	Transmit/Receive FIFO Access Register 0DH	CFDF30	16	16	2 or 3 PCLKB	2 ICLK
000A 85EEh	RSCAN	RAM Test Register 55	RPGACC55	16	16	2 or 3 PCLKB	2 ICLK
000A 85F0h to 000A 85FEh	RSCAN	RAM Test Register 56 to RAM Test Register 63	RPGACC56 to RPGACC63	16	16	2 or 3 PCLKB	2 ICLK
000A 8600h	RSCAN0	Transmit Buffer Register 0AL	TMIDL0	16	16	2 or 3 PCLKB	2 ICLK
000A 8600h	RSCAN	RAM Test Register 64	RPGACC64	16	16	2 or 3 PCLKB	2 ICLK
000A 8602h	RSCAN0	Transmit Buffer Register 0AH	TMIDH0	16	16	2 or 3 PCLKB	2 ICLK
000A 8602h	RSCAN	RAM Test Register 65	RPGACC65	16	16	2 or 3 PCLKB	2 ICLK
000A 8604h	RSCAN	RAM Test Register 66	RPGACC66	16	16	2 or 3 PCLKB	2 ICLK
000A 8606h	RSCAN0	Transmit Buffer Register 0BH	TMPTR0	16	16	2 or 3 PCLKB	2 ICLK
000A 8606h	RSCAN	RAM Test Register 67	RPGACC67	16	16	2 or 3 PCLKB	2 ICLK
000A 8608h	RSCAN0	Transmit Buffer Register 0CL	TMDF00	16	16	2 or 3 PCLKB	2 ICLK
000A 8608h	RSCAN	RAM Test Register 68	RPGACC68	16	16	2 or 3 PCLKB	2 ICLK
000A 860Ah	RSCAN0	Transmit Buffer Register 0CH	TMDF10	16	16	2 or 3 PCLKB	2 ICLK
000A 860Ah	RSCAN	RAM Test Register 69	RPGACC69	16	16	2 or 3 PCLKB	2 ICLK
000A 860Ch	RSCAN0	Transmit Buffer Register 0DL	TMDF20	16	16	2 or 3 PCLKB	2 ICLK
000A 860Ch	RSCAN	RAM Test Register 70	RPGACC70	16	16	2 or 3 PCLKB	2 ICLK
000A 860Eh	RSCAN0	Transmit Buffer Register 0DH	TMDF30	16	16	2 or 3 PCLKB	2 ICLK
000A 860Eh	RSCAN	RAM Test Register 71	RPGACC71	16	16	2 or 3 PCLKB	2 ICLK
000A 8610h	RSCAN0	Transmit Buffer Register 1AL	TMIDL1	16	16	2 or 3 PCLKB	2 ICLK
000A 8610h	RSCAN	RAM Test Register 72	RPGACC72	16	16	2 or 3 PCLKB	2 ICLK
000A 8612h	RSCAN0	Transmit Buffer Register 1AH	TMIDH1	16	16	2 or 3 PCLKB	2 ICLK
000A 8612h	RSCAN	RAM Test Register 73	RPGACC73	16	16	2 or 3 PCLKB	2 ICLK
000A 8614h	RSCAN	RAM Test Register 74	RPGACC74	16	16	2 or 3 PCLKB	2 ICLK
000A 8616h	RSCAN0	Transmit Buffer Register 1BH	TMPTR1	16	16	2 or 3 PCLKB	2 ICLK
000A 8616h	RSCAN	RAM Test Register 75	RPGACC75	16	16	2 or 3 PCLKB	2 ICLK
000A 8618h	RSCAN0	Transmit Buffer Register 1CL	TMDF01	16	16	2 or 3 PCLKB	2 ICLK
000A 8618h	RSCAN	RAM Test Register 76	RPGACC76	16	16	2 or 3 PCLKB	2 ICLK
000A 861Ah	RSCAN0	Transmit Buffer Register 1CH	TMDF11	16	16	2 or 3 PCLKB	2 ICLK
000A 861Ah	RSCAN	RAM Test Register 77	RPGACC77	16	16	2 or 3 PCLKB	2 ICLK
000A 861Ch	RSCAN0	Transmit Buffer Register 1DL	TMDF21	16	16	2 or 3 PCLKB	2 ICLK
000A 861Ch	RSCAN	RAM Test Register 78	RPGACC78	16	16	2 or 3 PCLKB	2 ICLK
000A 861Eh	RSCAN0	Transmit Buffer Register 1DH	TMDF31	16	16	2 or 3 PCLKB	2 ICLK
000A 861Eh	RSCAN	RAM Test Register 79	RPGACC79	16	16	2 or 3 PCLKB	2 ICLK
000A 8620h	RSCAN0	Transmit Buffer Register 2AL	TMIDL2	16	16	2 or 3 PCLKB	2 ICLK
000A 8620h	RSCAN	RAM Test Register 80	RPGACC80	16	16	2 or 3 PCLKB	2 ICLK
000A 8622h	RSCAN0	Transmit Buffer Register 2AH	TMIDH2	16	16	2 or 3 PCLKB	2 ICLK
000A 8622h	RSCAN	RAM Test Register 81	RPGACC81	16	16	2 or 3 PCLKB	2 ICLK
000A 8624h	RSCAN	RAM Test Register 82	RPGACC82	16	16	2 or 3 PCLKB	2 ICLK
000A 8626h	RSCAN0	Transmit Buffer Register 2BH	TMPTR2	16	16	2 or 3 PCLKB	2 ICLK
000A 8626h	RSCAN	RAM Test Register 83	RPGACC83	16	16	2 or 3 PCLKB	2 ICLK
000A 8628h	RSCAN0	Transmit Buffer Register 2CL	TMDF02	16	16	2 or 3 PCLKB	2 ICLK
000A 8628h	RSCAN	RAM Test Register 84	RPGACC84	16	16	2 or 3 PCLKB	2 ICLK
000A 862Ah	RSCAN0	Transmit Buffer Register 2CH	TMDF12	16	16	2 or 3 PCLKB	2 ICLK
000A 862Ah	RSCAN	RAM Test Register 85	RPGACC85	16	16	2 or 3 PCLKB	2 ICLK
000A 862Ch	RSCAN0	Transmit Buffer Register 2DL	TMDF22	16	16	2 or 3 PCLKB	2 ICLK
000A 862Ch	RSCAN	RAM Test Register 86	RPGACC86	16	16	2 or 3 PCLKB	2 ICLK
000A 862Eh	RSCAN0	Transmit Buffer Register 2DH	TMDF32	16	16	2 or 3 PCLKB	2 ICLK

Table 5.2 Recommended Operating Voltage Conditions

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Power supply voltages	VCC*1, *2	When USB is not used	1.8	—	5.5	V
		When USB is used When USB regulator is not used	3.0	—	3.6	
		When USB is used When USB regulator is used	4.0	—	5.5	
	VSS		—	0	—	
USB power supply voltages	VCC_USB	When USB regulator is not used	—	VCC	—	V
	VSS_USB		—	0	—	
VBATT power supply voltage	VBATT		1.8	—	5.5	V
Analog power supply voltages	AVCC0*1, *2		1.8	—	5.5	V
	AVSS0		—	0	—	
	VREFH0		1.8	—	AVCC0	
	VREFL0		—	0	—	
	VREFH		1.8	—	AVCC0	
	VREFL		—	0	—	

Note 1. Use AVCC0 and VCC under the following conditions:
AVCC0 and VCC can be set individually within the operating range when VCC ≥ 2.0 V
AVCC0 = VCC when VCC < 2.0 V
Note 2. When powering on the VCC and AVCC0 pins, power them on at the same time or the VCC pin first and then the AVCC0 pin.



Note 1. All peripheral operations except any BGO operation are operating normally. Indicates the average of the typical samples through actual measurement during product evaluation.
Note 2. All peripheral operations except any BGO operation are operating at maximum. Indicates the average of the upper-limit samples through actual measurement during product evaluation.

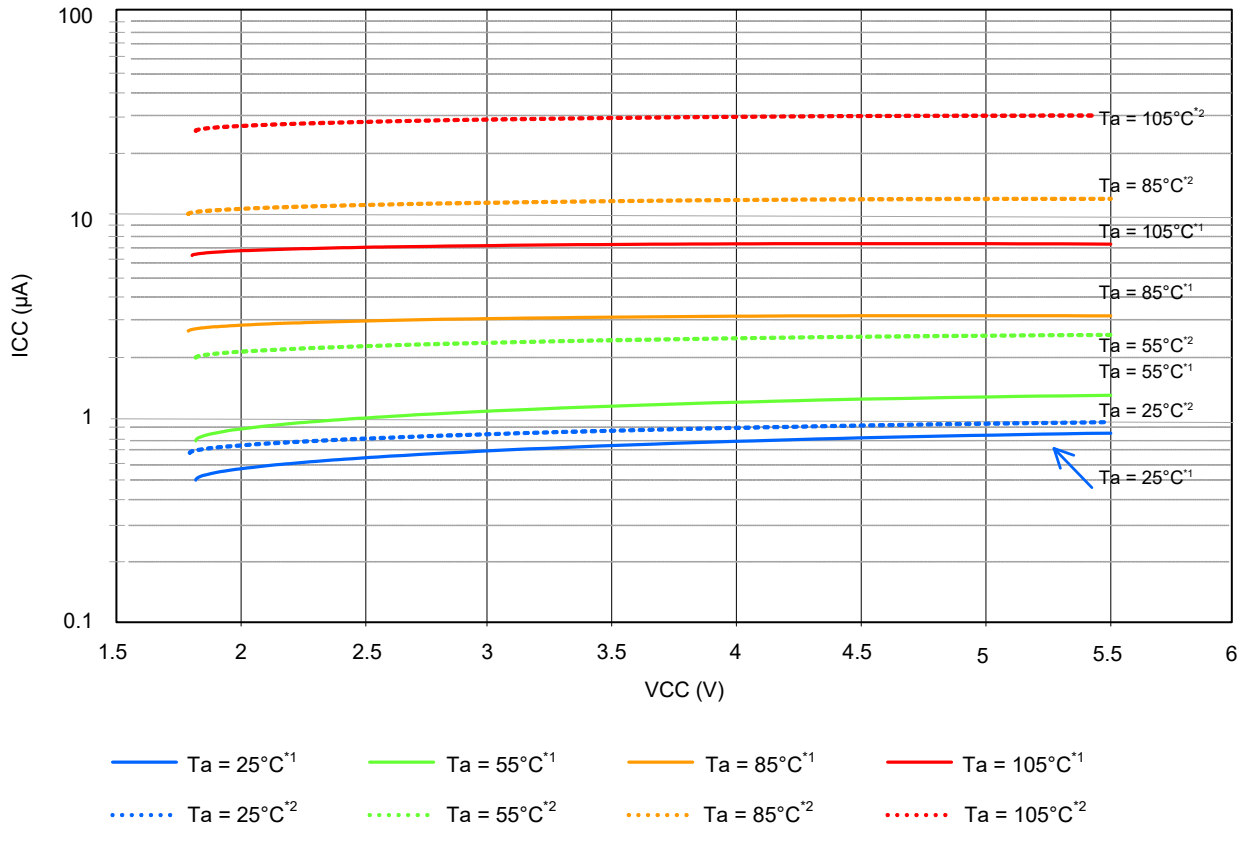
Figure 5.2 Voltage Dependency in Middle-Speed Operating Mode (Reference Data)

Table 5.8 DC Characteristics (6)

Conditions: 1.8 V ≤ VCC= VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

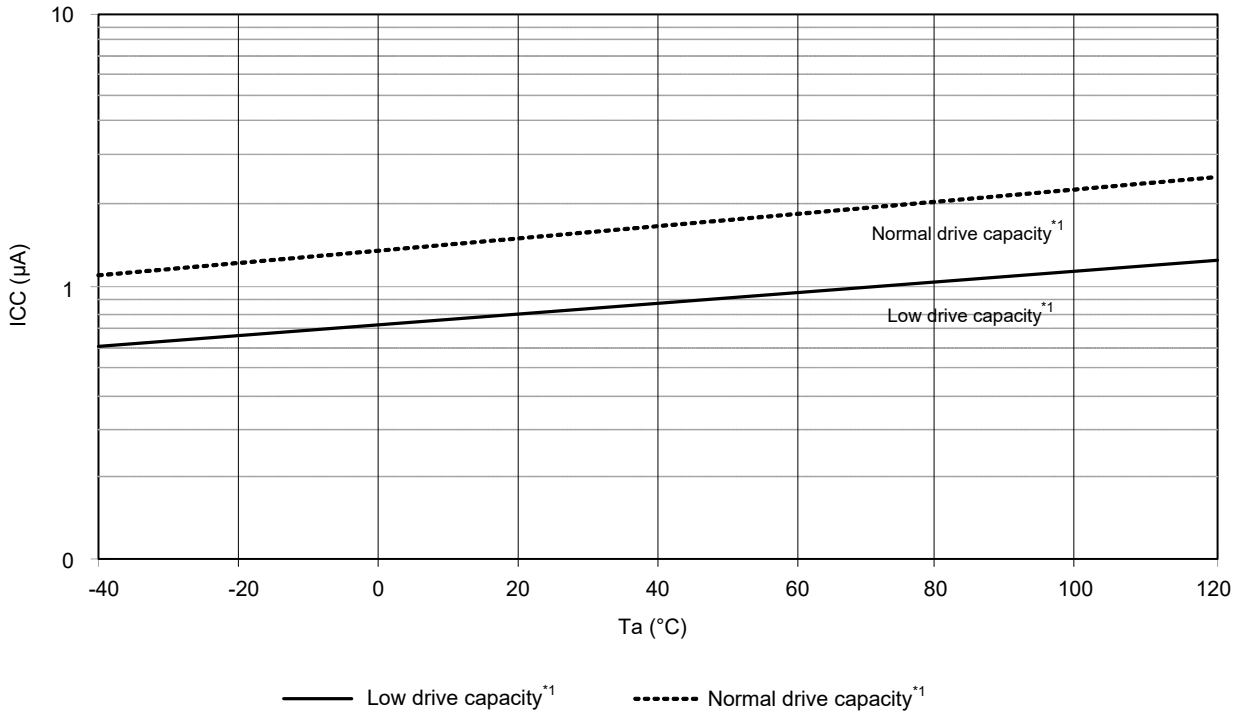
Item			Symbol	Typ.*3	Max.	Unit	Test Conditions
Supply current*1	Software standby mode*2	T_a = 25°C	I_{CC}	0.8	3.7	μA	
		T_a = 55°C		1.2	4.3		
		T_a = 85°C		3.5	18.6		
		T_a = 105°C		7.9	45.2		
	Increment for IWDT operation			0.4	—		
	Increment for LPT operation			0.4	—		Use IWDT-Dedicated On-Chip Oscillator for clock source
	Increment for RTC operation*4			0.4	—		RCR3.RTCDV[2:0] set to low drive capacity
				1.2	—		RCR3.RTCDV[2:0] set to normal drive capacity

Note 1. Supply current values are with all output pins unloaded and all input pull-up MOSs in the off state.
Note 2. The IWDT, LVD, and CMPB are stopped.
Note 3. When VCC is 3.3 V.
Note 4. This increment includes the oscillation circuit.



Note 1. Indicates the average of the typical samples through actual measurement during product evaluation.
Note 2. Indicates the average of the upper-limit samples through actual measurement during product evaluation.

Figure 5.4 Voltage Dependency in Software Standby Mode (Reference Data)



Note 1. Indicates the average of the typical samples through actual measurement during product evaluation.

Figure 5.6 Temperature Dependency of RTC Operation with VCC Off (Reference Data)

Table 5.10 DC Characteristics (8)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Permissible total power consumption*1	Pd	—	—	350	mW	D-version product
Permissible total power consumption*1	Pd	—	—	130	mW	G-version product

Note: Please contact a Renesas Electronics sales office for information on the derating of the G-version product. Derating is the systematic reduction of load to improve reliability.

Note 1. Total power dissipated by the entire chip (including output currents)

Table 5.11 DC Characteristics (9)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.*7	Max.	Unit	Test Conditions
Analog power supply current	During A/D conversion (at high-speed conversion)	I_{AVCC}	—	0.7	1.7	mA	
	During A/D conversion (in low-current mode)		—	0.6	1.0		
	During D/A conversion (per channel)*1		—	0.4	0.8		
	Waiting for A/D and D/A conversion (all units)		—	—	0.4	μA	
Reference power supply current	During A/D conversion (at high-speed conversion)	I_{REFH0}	—	25	150	μA	
	Waiting for A/D conversion (all units)		—	—	60	nA	
	During D/A conversion (per channel)	I_{REFH}	—	50	100	μA	
	Waiting for D/A conversion (all units)		—	—	100	nA	
LVD1, 2	per channel	I_{LVD}	—	0.15	—	μA	
Temperature sensor*6	—	I_{TEMP}	—	75	—	μA	
Comparator B operating current*6	Window mode	I_{CMP}*5	—	12.5	28.6	μA	
	Comparator high-speed mode (per channel)		—	3.2	16.2	μA	
	Comparator low-speed mode (per channel)		—	1.7	4.4	μA	
CTSU operating current	When sleep mode Base clock frequency: 2MHz Pin capacitance: 50pF	I_{CTSU}	—	150	—	μA	
USB operating current*4	During USB communication operation under the following settings and conditions • Host controller operation is set to full-speed mode Bulk OUT transfer (64 bytes) × 1, bulk IN transfer (64 bytes) × 1 • Connect peripheral devices via a 1-meter USB cable from the USB port.	I_{USBH}*2	—	4.3 (VCC) 0.9 (VCC_USB)	—	mA	
	During USB communication operation under the following settings and conditions • Function controller operation is set to full-speed mode Bulk OUT transfer (64 bytes) × 1, bulk IN transfer (64 bytes) × 1 • Connect the host device via a 1-meter USB cable from the USB port.	I_{USBF}*2	—	3.6 (VCC) 1.1 (VCC_USB)	—	mA	
	During suspended state under the following setting and conditions • Function controller operation is set to full-speed mode (pull up the USB0_DP pin) • Software standby mode • Connect the host device via a 1-meter USB cable from the USB port.	I_{SUSP}*3	—	0.35 (VCC) 170 (VCC_USB)	—	μA	

Note 1. The value of the D/A converter is the value of the power supply current including the reference current.
Note 2. Current consumed only by the USB module.
Note 3. Includes the current supplied from the pull-up resistor of the USB0_DP pin to the pull-down resistor of the host device, in addition to the current consumed by this MCU during the suspended state.
Note 4. Current consumed by the power supplies (VCC and VCC_USB).
Note 5. Current consumed only by the comparator B module.
Note 6. Current consumed by the power supply (VCC).
Note 7. When VCC = AVCC0 = VCC_USB = 3.3 V.

Table 5.12 DC Characteristics (10)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
RAM standby voltage	V_{RAM}	1.8	—	—	V	

Table 5.17 Permissible Output Currents (2)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item			Symbol	Max.	Unit
Permissible output low current (average value per pin)	Ports 40 to 47, ports 03, 05, 07, port 36, 37		I_{OL}	4.0	mA
	Ports other than above	Normal output mode		4.0	
		High-drive output mode		8.0	
Permissible output low current (maximum value per pin)	Ports 40 to 47, ports 03, 05, 07, ports 36, 37			4.0	
	Ports other than above	Normal output mode		4.0	
		High-drive output mode		8.0	
Permissible output low current	Total of ports 40 to 47, ports 03, 05, 07		ΣI_{OL}	30	
	Total of ports 12 to 17, ports 20 to 27, ports 30 to 37, port PJ3			30	
	Total of ports 50 to 55, ports C0 to C7, ports B0 to B7			30	
	Total of ports E0 to E7, ports A0 to A7, ports D0 to D4			30	
	Total of all output pins			60	
Permissible output high current (average value per pin)	Ports 40 to 47, ports 03, 05, 07, ports 36, 37		I_{OH}	–4.0	
	Ports other than above	Normal output mode		–4.0	
		High-drive output mode		–8.0	
Permissible output high current (maximum value per pin)	Ports 40 to 47, ports 03, 05, 07, ports 36, 37			–4.0	
	Ports other than above	Normal output mode		–4.0	
		High-drive output mode		–8.0	
Permissible output high current	Total of ports 40 to 47, ports 03, 05, 07		ΣI_{OH}	–30	
	Total of ports 12 to 17, ports 20 to 27, ports 30 to 37, port PJ3			–30	
	Total of ports 50 to 55, ports C0 to C7, ports B0 to B7			–30	
	Total of ports E0 to E7, ports A0 to A7, ports D0 to D4			–30	
	Total of all output pins			–60	

Note: Do not exceed the permissible total supply current.

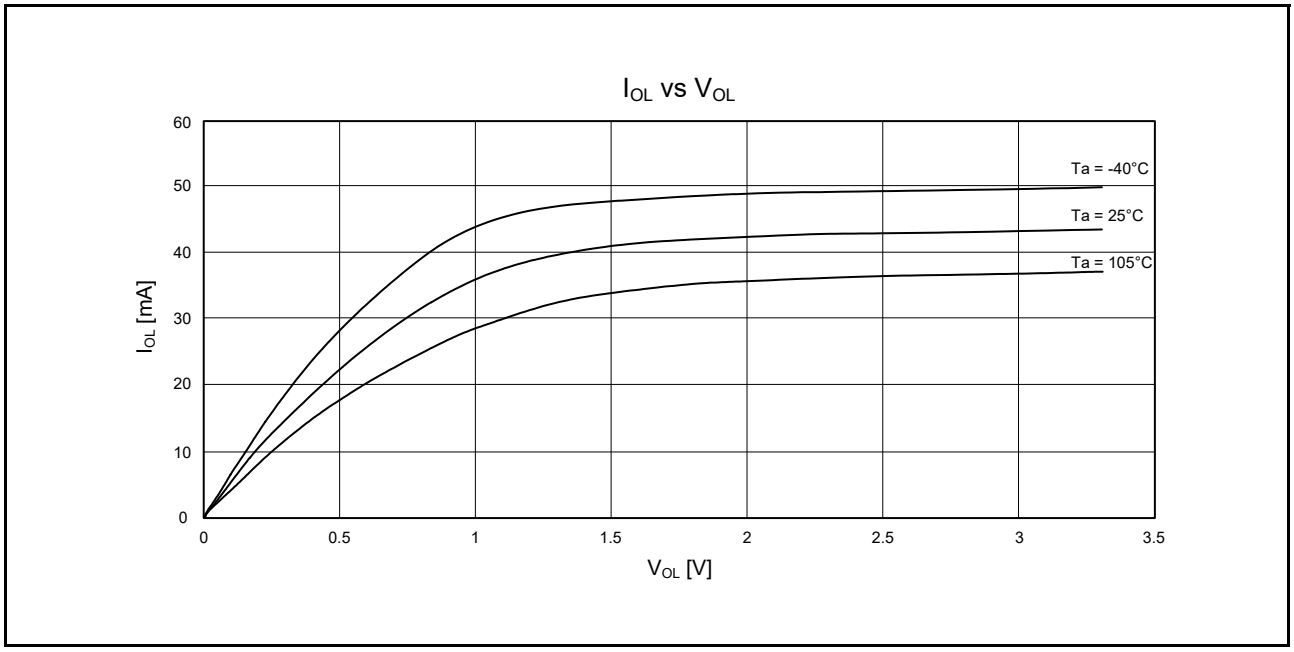


Figure 5.20 V_{OL} and I_{OL} Temperature Characteristics of RIIC Output Pin at VCC = 3.3 V (Reference Data)

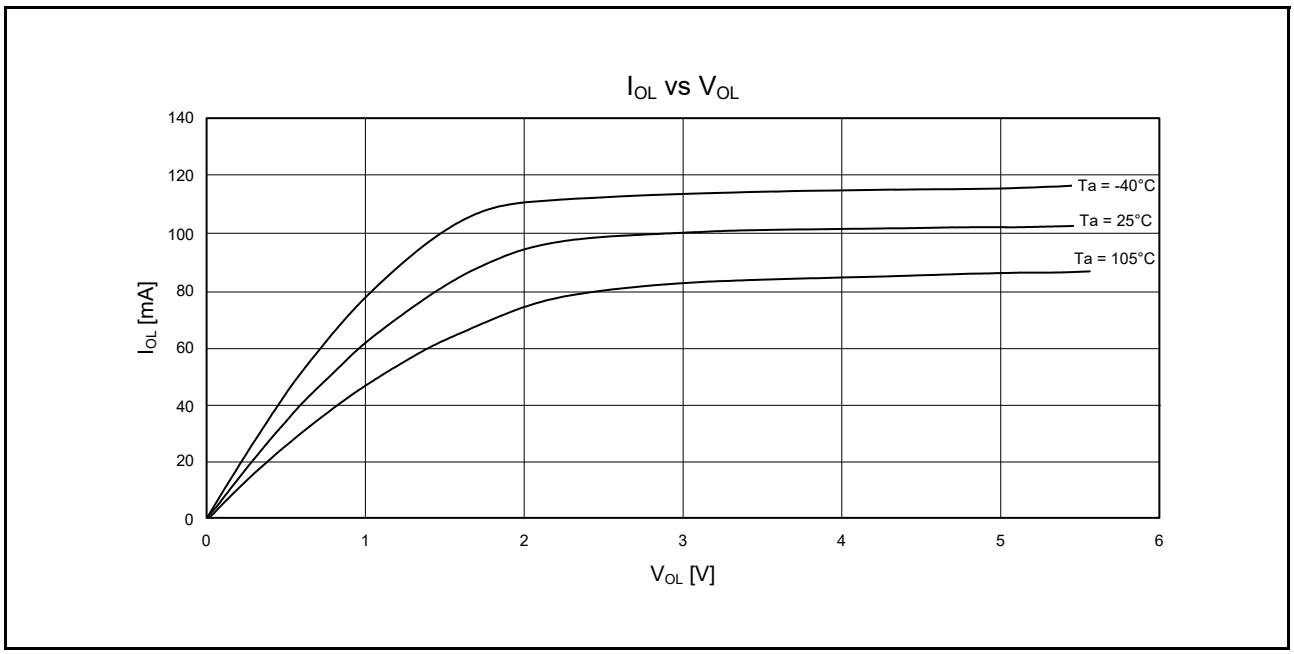


Figure 5.21 V_{OL} and I_{OL} Temperature Characteristics of RIIC Output Pin at VCC = 5.5 V (Reference Data)

Table 5.30 Timing of Recovery from Low Power Consumption Modes (3)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	Low-speed mode	Sub-clock oscillator operating	t_{SBYSC}	—	600	750	µs	Figure 5.34

Note 1. The sub-clock continues oscillating in software standby mode during low-speed mode.

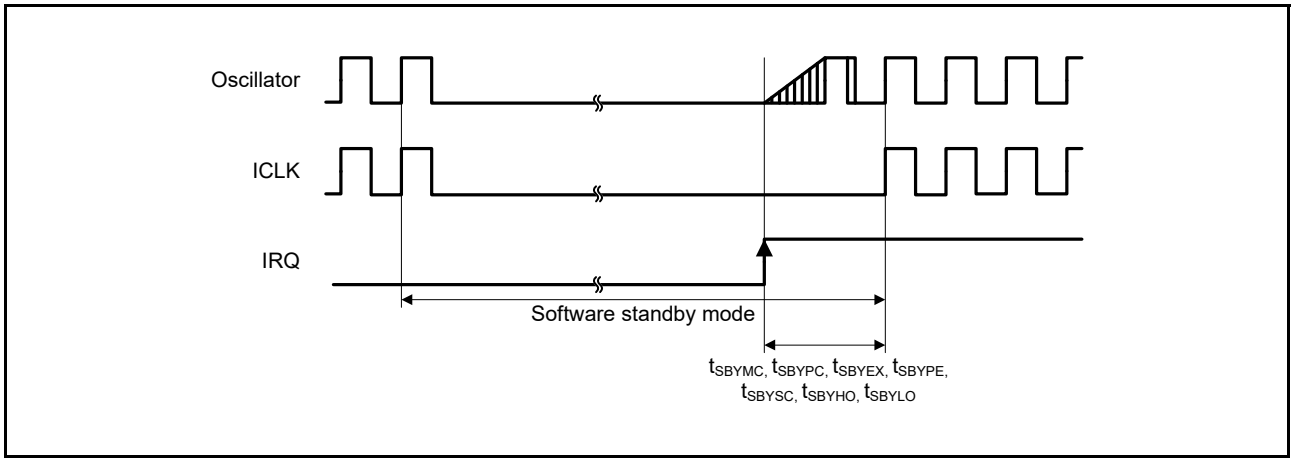


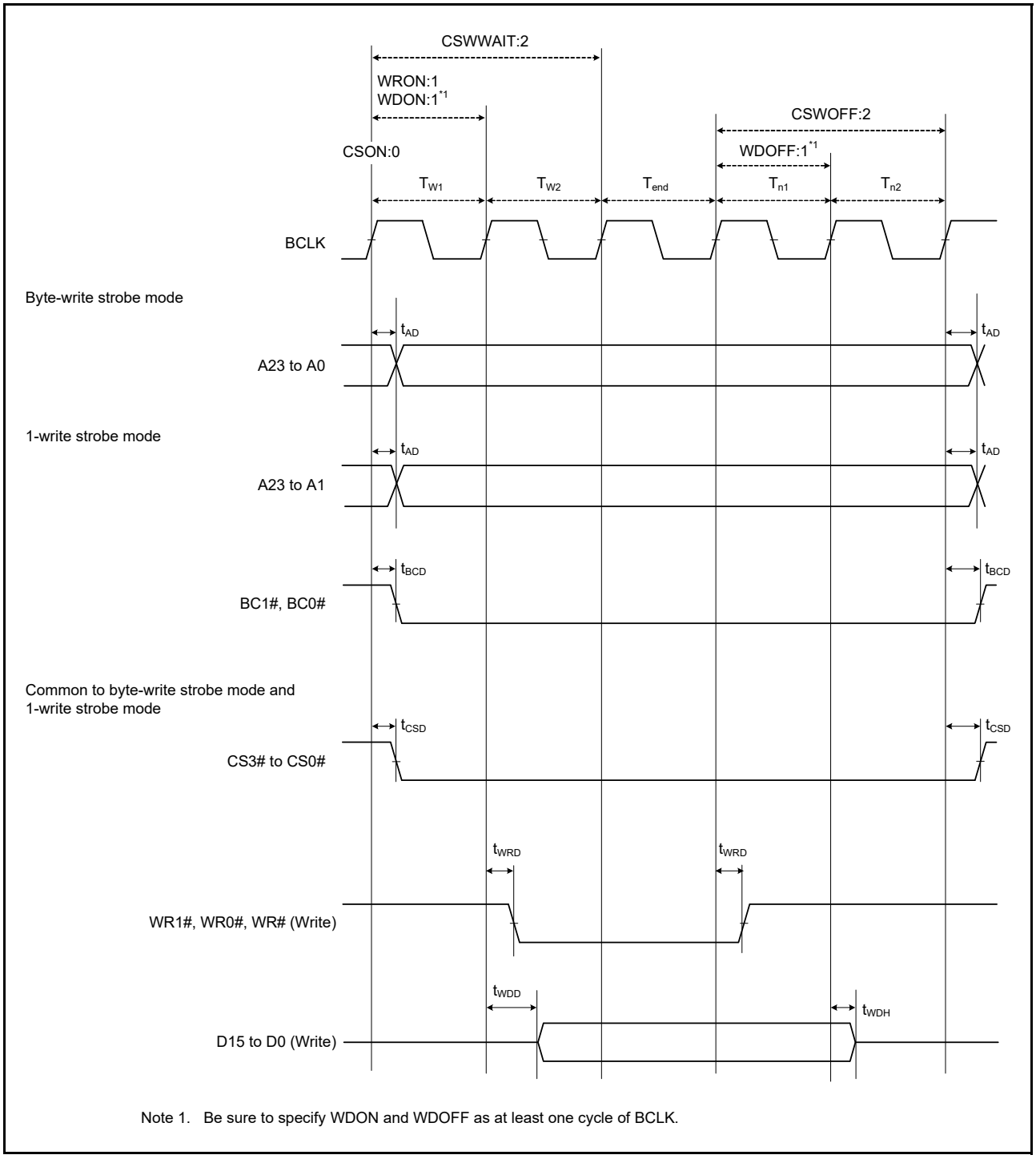
Figure 5.34 Software Standby Mode Recovery Timing

Table 5.31 Timing of Recovery from Low Power Consumption Modes (4)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from deep sleep mode*1	High-speed mode*2	t_{DSLP}	—	2	3.5	µs	Figure 5.35
	Middle-speed mode*3	t_{DSLP}	—	3	4	µs	
	Low-speed mode*4	t_{DSLP}	—	400	500	µs	

Note 1. Oscillators continue oscillating in deep sleep mode.
Note 2. When the frequency of the system clock is 32 MHz.
Note 3. When the frequency of the system clock is 12 MHz.
Note 4. When the frequency of the system clock is 32 kHz.



Note 1. Be sure to specify WDON and WDOFF as at least one cycle of BCLK.

Figure 5.39 External Bus Timing/Normal Write Cycle (Bus Clock Synchronization)

Table 5.40 Timing of On-Chip Peripheral Modules (3)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Max.	Unit*1	Test Conditions
Simple SPI	SCK clock cycle output (master)		t_{SPcyc}	4	65536	t_{Pcyc}	Figure 5.54
	SCK clock cycle input (slave)			6	65536	t_{Pcyc}	
	SCK clock high pulse width		t_{SPCKWH}	0.4	0.6	t_{SPcyc}	
	SCK clock low pulse width		t_{SPCKWL}	0.4	0.6	t_{SPcyc}	
	SCK clock rise/fall time		t_{SPCKr}, t_{SPCKf}	—	20	ns	
	Data input setup time (master)	2.7 V or above	t_{SU}	65	—	ns	Figure 5.55, Figure 5.56
		1.8 V or above		95	—		
	Data input setup time (slave)			40	—		
	Data input hold time		t_H	40	—	ns	
	SSL input setup time		t_{LEAD}	3	—	t_{SPcyc}	
	SSL input hold time		t_{LAG}	3	—	t_{SPcyc}	
	Data output delay time (master)		t_{OD}	—	40	ns	
	Data output delay time (slave)	2.7 V or above		—	65		
		1.8 V or above		—	100		
	Data output hold time (master)	2.7 V or above	t_{OH}	–10	—	ns	
		1.8 V or above		–20	—		
	Data output hold time (slave)			–10	—		
	Data rise/fall time		t_{Dr}, t_{Df}	—	20	ns	
	SSL input rise/fall time		t_{SSLr}, t_{SSLf}	—	20	ns	
	Slave access time		t_{SA}	—	6	t_{Pcyc}	Figure 5.57, Figure 5.58
	Slave output release time		t_{REL}	—	6	t_{Pcyc}	

Note 1. t_{Pcyc}: PCLK cycle

Table 5.49 A/D Conversion Characteristics (4)

Conditions: 2.4V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5V, 2.4V ≤ VREFH0 ≤ AVCC0, VSS = AVSS0 = VSS_USB = 0V, reference voltage = VREFH0 selected, Ta = –40 to +105°C

Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		1	—	16	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 16 MHz)	Permissible signal source impedance (Max.) = 2.2 kΩ	3.38	—	—	µs	High-precision channel The ADCSR.ADHSC bit is 1 The ADSSTRn register is 0Dh
		5.06	—	—		Normal-precision channel The ADCSR.ADHSC bit is 1 The ADSSTRn register is 28h
Analog input capacitance	Cs	—	—	15	pF	Pin capacitance included Figure 5.68
Analog input resistance	Rs	—	—	2.5	kΩ	Figure 5.68
Offset error		—	±0.5	±4.5	LSB	
Full-scale error		—	±0.75	±4.5	LSB	
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±1.25	±5.0	LSB	High-precision channel
				±8.0	LSB	Other than above
DNL differential non-linearity error		—	±1.0	—	LSB	
INL integral non-linearity error		—	±1.0	±3.0	LSB	

Note: The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential non-linearity error, and INL integral non-linearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

5.7 Temperature Sensor Characteristics

Table 5.55 Temperature Sensor Characteristics

Conditions: 2.0 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Relative accuracy	—	—	±1.5	—	°C	2.4 V or above
		—	±2.0	—		Below 2.4 V
Temperature slope	—	—	–3.65	—	mV/°C	
Output voltage (25°C)	—	—	1.05	—	V	VCC = 3.3 V
Temperature sensor start time	t_{START}	—	—	5	µs	
Sampling time	—	5	—	—	µs	

5.8 Comparator Characteristics

Table 5.56 Comparator Characteristics

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
CVREFB0 to CVREFB3 input reference voltage		VREF	0	—	VCC - 1.4	V	
CMPB0 to CMPB3 input voltage		VI	–0.3	—	VCC + 0.3	V	
Offset	Comparator high-speed mode	—	—	—	50	mV	
	Comparator high-speed mode Window function enabled	—	—	—	60	mV	
	Comparator low-speed mode	—	—	—	40	mV	
Comparator output delay time	Comparator high-speed mode	Td	—	—	1.2	µs	VCC = 3 V, input slew rate ≥ 50 mV/us
	Comparator high-speed mode Window function enabled	Tdw	—	—	2.0	µs	
	Comparator low-speed mode	Td	—	—	5.0	µs	
High-side reference voltage (comparator high-speed mode, window function enabled)		VRFH	—	0.76 VCC	—	V	
Low-side reference voltage (comparator high-speed mode, window function enabled)		VRFL	—	0.24 VCC	—	V	
Operation stabilization wait time		Tcmp	100	—	—	µs	

5.13 ROM (Flash Memory for Code Storage) Characteristics

Table 5.62 ROM (Flash Memory for Code Storage) Characteristics (1)

Item		Symbol	Min.	Typ.	Max.	Unit	Conditions
Reprogramming/erasure cycle*1		N_{PEC}	1000	—	—	Times	
Data hold time	After 1000 times of N_{PEC}	t_{DRP}	20*2, *3	—	—	Year	T_a = +85°C

Note 1. Definition of reprogram/erase cycle: The reprogram/erase cycle is the number of erasing for each block. When the reprogram/erase cycle is n times (n = 1000), erasing can be performed n times for each block. For instance, when 4-byte programming is performed 256 times for different addresses in a 1-Kbyte block and then the entire block is erased, the reprogram/erase cycle is counted as one. However, programming the same address for several times as one erasing is not enabled (overwriting is prohibited).
Note 2. Characteristic when using the flash memory programmer and the self-programming library provided from Renesas Electronics.
Note 3. This result is obtained from reliability testing.

Table 5.63 ROM (Flash Memory for Code Storage) Characteristics (2) High-Speed Operating Mode

Conditions: 2.7 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V

Temperature range for the programming/erasure operation: T_a = –40 to +105°C

Item		Symbol	FCLK = 1 MHz			FCLK = 32 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	
Programming time	8-byte	t_{P8}	—	112	967	—	52.3	491	µs
Erasure time	2-Kbyte	t_{E2K}	—	8.75	278	—	5.50	215	ms
	512-Kbyte (when block erase command is used)	t_{E512K}	—	928	19218	—	72.0	1679	ms
	512-Kbyte (when all-block erase command is used)	t_{EA512K}	—	923	19013	—	66.7	1469	ms
Blank check time	8-byte	t_{BC8}	—	—	55.0	—	—	16.1	µs
	2-Kbyte	t_{BC2K}	—	—	1840	—	—	136	ms
Erase operation forced stop time		t_{SED}	—	—	18.0	—	—	10.7	µs
Start-up area switching setting time		t_{SAS}	—	12.3	566.5	—	6.2	434	ms
Access window time		t_{AWS}	—	12.3	566.5	—	6.2	434	ms
ROM mode transition wait time 1		t_{DIS}	2.0	—	—	2.0	—	—	µs
ROM mode transition wait time 2		t_{MS}	5.0	—	—	5.0	—	—	µs

Note: The time until each operation of the flash memory is started after instructions are executed by software is not included.
Note: The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note: The frequency accuracy of FCLK must be within ±3.5%.

Rev.	Date	Description		Classification
		Page	Summary	
1.20	Sep 28, 2018	95	Figure 5.12 VOH/VOL and IOH/IOL Temperature Characteristics at VCC = 5.5 V When Normal Output is Selected (Reference Data), changed	TN-RX*-A201A/E
		124	Table 5.44 Timing of On-Chip Peripheral Modules (7), added	TN-RX*-A197A/E
		131	Figure 5.64 SD Host Interface Input/Output Signal Timing, added	TN-RX*-A197A/E
		132	Table 5.45 USB Characteristics (USB0_DP and USB0_DM Pin Characteristics) conditions, changed	

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